

Harvatek Surface Mount LED Data Sheet HT-193NB-5589

Official Product	Product: HT-193NB-5589	Data Sheet No.		
Tentative Product	*******	HT-193NB-5589		
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DISCLAIMER	3
PRODUCT SPECIFICATIONS	4
LABEL SPECIFICATIONS	5
LUMINOUS INTENSITY (IV) BIN:	6
■ WAVELENGTH (AD) BIN:	6
FORWARD VOLTAGE (V _F) BIN:	6
@20MA / TA=25°C, TOLERANCE: + 0.05 V	6
PRODUCT CHARACTERISTICS	7
ABSOLUTE MAXIMUM RATINGS	7
ELECTRO-OPTICAL CHARACTERISTICS	7
PACKAGE OUTLINE DIMENSION	
CHARACTERISTIC CURVES FOR NB	
CHARACTERISTIC CURVES (RADIATION PATTERN)	8
PACKAGING	9
TAPE DIMENSION	9
REEL DIMENSION	9
Packing	10
DRY PACK	11
REFLOW SOLDERING	12
PRECAUTIONS	13
Reworking	13
CLEANING	13
REVISION HISTORY	14

Official Product	Product: HT-193NB-5589	Data Sheet No.		
Tentative Product	******	HT-193NB-5589		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 2/14



DISCLAIMER

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- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Official Product	Product: HT-193NB-5589	Data Sheet No.		
Tentative Product	********	HT-193NB-5589		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 3/14



Product Specifications

Product	Emission Color	Technology	Test Current I _F (mA)	Luminous Intensity I _V (mcd)	Forward Voltage V _F (V)	Orderable Part Number
HT-193NB	Blue	InGaN	20	45 typ.	3.3 typ.	HT-193NB-YYYY
	Specification		Material			Quantity
Resin	Defused		Epoxy resin			
Carrier tape	Per EIA 481-1A specs		Conductive black tape			4000pcs per reel
Reel	Per EIA 481-1A specs		Conductive black			
Label	HT standard		Paper			
Packing bag	220x240mm		Aluminum laminated bag/ no-zipper		One reel per bag	
Carton	HT standard		Paper			

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are

STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

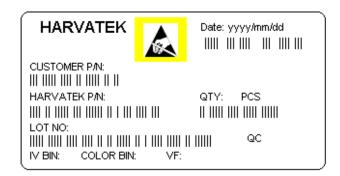
Compliance and Certified ISO9002, QS9000 and ISO14001 Certified RoHS Compliant



Official Product	Product: HT-193NB-5589	Data Sheet No.		
Tentative Product	*******	HT-193NB-5589		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 4/14



Label Specifications



■ Harvatek P/N:



Series Name	Emitting Color	Customer Code
HT-193		
HT: Harvatek	NB: Blue	5589
193: 0603 0.4mm series 1.6 (L) x 0.8 (W) x 0.4 (H) mm		Customer Product Code
Viewing Angle: 140°		

Lot No.:

1 2 3 4 5 6 7 8 9 10

P 1 2 2 3 0 A - D T

Code 1	Code 2	Code 3	Code 4, 5	Code 6, 7	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Lots	Resin Color	Packaging
		1: Jan.				
	Z: 2000	2: Feb.				
Internal	1: 2001			04.00	C: Clear	
Tracing	2: 2002	9: Sep.	1~31/ (30)	01~99,	D: Diffused	T: Tape & Reel
Code	3: 2003	A: Oct.		A,B,C		
		B: Nov.				
		C: Dec.				

Official Product	Product: HT-193NB-5589			Data Sheet No.
Tentative Product	*******			HT-193NB-5589
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 5/14



■ Luminous Intensity (Iv) Bin:

Bin	Luminous Intens	sity Range (mcd)
Biii	Minimum	Maximum
N	28.5	45.0
Р	45.0	71.5
Q	71.5	112.5

@20mA / Ta=25° C, Tolerance: <u>+</u> 10%

■ Wavelength (λ_D) Bin:

	Wavelength Range (nm)				
Bin	Blue				
	(N	IB)			
	Min	Max			
В	464.0	468.0			
С	468.0	472.0			
D	472.0 476.0				

@20mA / Ta=25° C, Tolerance: ± 0.5nm

■ Forward Voltage (V_F) Bin:

Color	Bin Code	Spec. Range
Blue		3.9 V max
(NB)	-	3.9 V IIIax

@20mA / Ta=25°C, Tolerance: <u>+</u> 0.05 V

Official Product	Product: HT-193NB-5589	Data Sheet No.		
Tentative Product	*******	*******		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 6/14



Product Characteristics

Absolute Maximum Ratings							
Product	Emission Color	P _d (mW)	I _F (mA)	I _{FP} * (mA)	V _R (V)	T _{OP} (°C)	T _{ST} (°C)
HT-193NB	Blue	78	20	80	5	-30°C~+80°C	-40°C~+85°C

^{*} Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

Electro-Optical Characteristics

(Ta 25 °C)

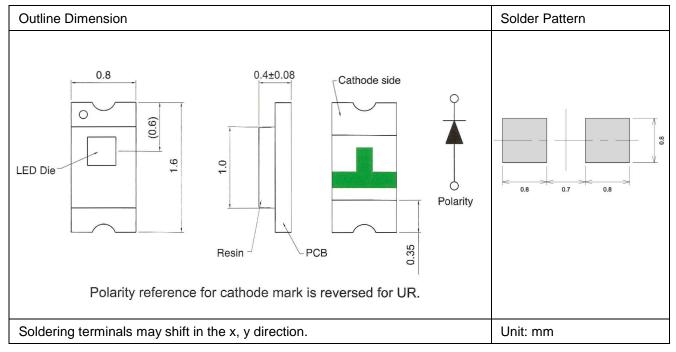
	Fulliation		V _F (V)		λ(nm)			I [*] ∨(mcd)	
Product	Emission Color	I _F (mA)	typ.	max	λ	λ P	Δλ	min	typ.
HT-193NB	Blue	20	3.3	3.9	470	468	40	28	40

^{*} Per NIST standards

Package Outline Dimension

Recommended Soldering Pattern for Reflow Soldering

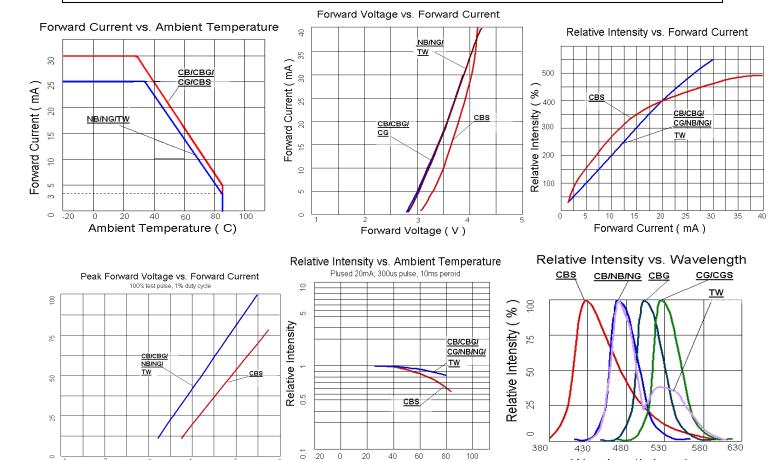
Unit: mm Tolerance: +/-0.1



Official Product	Product: HT-193NB-5589			Data Sheet No.
Tentative Product	******	*******		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 7/14



Characteristic Curves for NB

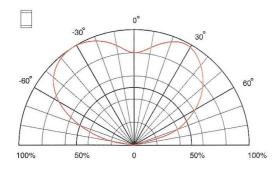


Temperature (C)

Characteristic Curves (Radiation Pattern)

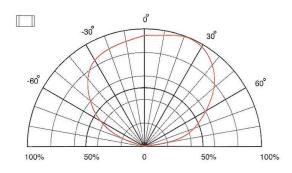
Forward Voltage (V)

Directive Characteristics



Directive Characteristics

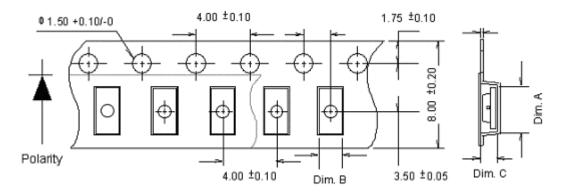
Wavelength (nm)



Official Product	Product: HT-193NB-5589			Data Sheet No.
Tentative Product	*******	*******		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 8/14



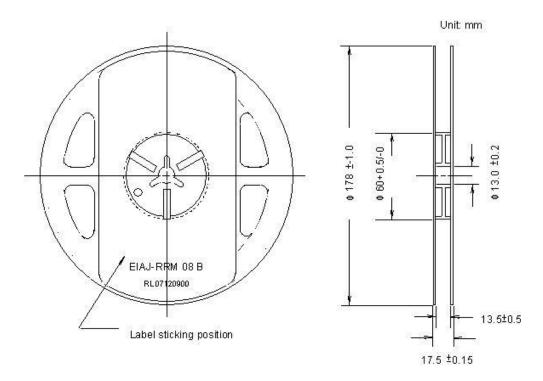
Packaging Tape Dimension



Part No.	Dim. A	Dim. B	Dim. C	Q'ty/Reel
HT-193	1.80±0.10	0.95±0.10	0.60±0.10	4K

Unit: mm

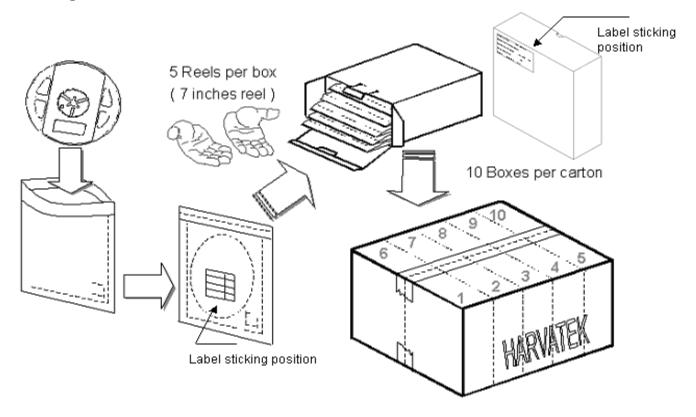
Reel Dimension



Official Product	Product: HT-193NB-5589			Data Sheet No.
Tentative Product	******			HT-193NB-5589
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 9/14



Packing



5 boxes per carton is available depending on shipment quantity.

	Specification	Material	Quantity
Carrier tape	Per EIA 481-1A specs	Conductive black tape	4000pcs per reel
Reel	Per EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specified

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Official Product	Product: HT-193NB-5589	Data Sheet No.		
Tentative Product	*******			HT-193NB-5589
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 10/14

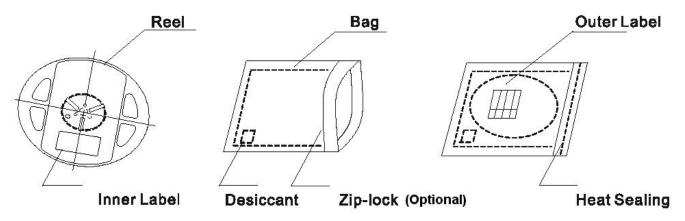


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



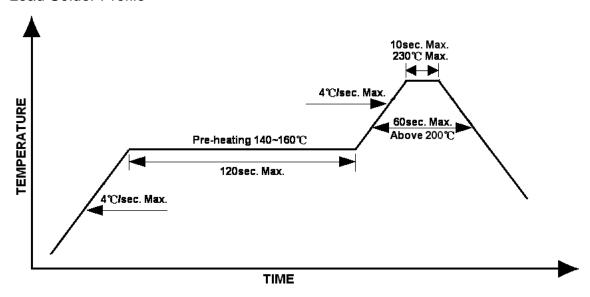
Official Product	Product: HT-193NB-5589	Data Sheet No.		
Tentative Product	*******	******		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 11/14



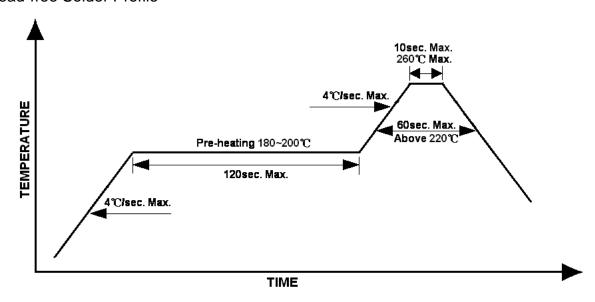
Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead Solder Profile



Lead-free Solder Profile



Official Product	Product: HT-193NB-5589	Data Sheet No.		
Tentative Product	******	******		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 12/14



Precautions

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Official Product	Product: HT-193NB-5589	Data Sheet No.		
Tentative Product	*******	******		
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 13/14



Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release – 5589		1.0	10-29-2009

Official Product	Product: HT-193NB-5589			Data Sheet No.
Tentative Product	********			HT-193NB-5589
Specifications are subject to change without notice. Data and drawings herein are copyrighted.		October 29, 2009	Version of 1.0	Page 14/14